

IN THE CLAIMS:

Please cancel claims 1 - 7 of the International Application and replace them with the following claims. The status of the claims after amendment will be as follows:

Claims 1 - 7 (cancelled)

8. (new) A lead-free solder paste comprising a first solder alloy powder of a first solder alloy, a second solder alloy powder of a second solder alloy, and a flux mixed with the first and second solder alloy powders, wherein the first solder alloy and the solder alloy have a difference of at least 10°C in their main peak temperatures measured by differential thermal analysis, and the overall composition after melting of the first and second solder alloy powders is 3 - 4 mass % of Ag, 3 - 10 mass % of In, 0 - 1 mass % of Bi, 0 - 1 mass % Cu, and a balance of Sn.

9. (new) A solder paste as claimed in claim 8 wherein the first solder alloy is a Sn-Ag-In alloy and the second solder alloy is a Sn-Ag alloy.

10. (new) A solder paste as claimed in claim 9 wherein:
the first solder alloy contains 3 - 4 mass % of Ag and 6 - 20 mass % of In; and
the second solder alloy contains 3 - 4 mass % of Ag.

11. (new) A solder paste as claimed in claim 8 wherein:
at least one of the first and second solder alloys contains
Bi;

the first solder alloy is selected from a Sn-Ag-In alloy and
a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag alloy, a
Sn-Ag-Bi alloy, a Sn-Ag-Cu alloy, and a Sn-Ag-Bi-Cu alloy.

12. (new) A solder paste as claimed in claim 11 wherein:
the first solder alloy contains 3 - 4 mass % of Ag and 6 -
20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

13. (new) A solder paste as claimed in claim 8 wherein:
the first solder alloy is selected from a Sn-Ag-In alloy and
a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag-Cu alloy
and a Sn-Ag-Bi-Cu alloy.

14. (new) A solder paste as claimed in claim 13 wherein:
the first solder alloy contains 3 - 4 mass % of Ag and 6 -
20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

15. (new) A solder paste as claimed in claim 8 wherein the
first solder alloy has a lower main peak temperature measured by
differential thermal analysis than the second solder alloy.